

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Amitec-Advanced Multilayer Interconnect Technologies Ltd.	08/03/2011
RECEIVING PARTY DATA	
Name:	Zhuhai Advanced Chip Carriers & Electronic Substrate Solutions Technologies Co. Ltd.
Street Address:	FounderPCB Industry Park, Fushan Industry Zone, Qianwu, Doumen
City:	Zhuhai
State/Country:	CHINA
Postal Code:	519173
PROPERTY NUMBERS Total: 3	
Property Type	Number
Patent Number:	7635641
Patent Number:	7669320
Patent Number:	7682972
CORRESPONDENCE DATA	
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Address Line 4:	Jerusalem, ISRAEL 91450
ATTORNEY DOCKET NUMBER:	AMIT 1047/901
NAME OF SUBMITTER:	Yotam Stern
Total Attachments: 2 source=ASSIGNMENT AMIT 1047 901#page1.tif source=Recordation form AMIT 1047 901#page1.tif	

OP \$120.00 7635641

PATENT

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REEL: 026698 FRAME: 0579

ASSIGNMENT

For good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, the undersigned

Amitec - Advanced Multilayer Interconnect Technologies Ltd., POB 631, Migdal Haemek 23105, ISRAEL

(hereinafter called the "Assignor"),

hereby sells, assigns and transfers to

Zhuhai Advanced Chip Carriers & Electronic Substrate Solutions Technologies Co. Ltd., FounderPCB Industry Park, Fushan Industry Zone, Qianwu, Doumen, Zhuhai, P.R.China. 519173

(hereinafter called the "Assignee"), its successors, assigns, nominees or other legal representatives, the undersigned's entire right, title and interest in and to the inventions titled

1. INTEGRATED CIRCUIT SUPPORT STRUCTURES AND THEIR FABRICATION
2. CORELESS CAVITY SUBSTRATES FOR CHIP PACKAGING AND THEIR FABRICATION
3. ADVANCED MULTILAYER CORELESS SUPPORT STRUCTURES AND METHOD FOR THEIR FABRICATION

described and claimed in


1. U.S. Patent No. 7,635,641 issued on December 22, 2009
2. U.S. Patent No. 7,669,320 issued on March 2, 2010
3. U.S. Patent No. 7,682,972 issued on March 23, 2010

and in and to said patents and all patents and patent applications derived therefrom, and all original and reissued patents granted therefor, and any and all continuations and divisions thereof, including, but not limited to, any and all extensions, reexaminations, substitutes and renewals, and including the right to apply for and obtain patents in all other countries, the priority rights under International Conventions, and any and all Letters Patent which may be granted thereon; all rights to collect and retain all royalties and other considerations arising from said patents; and all rights to sue for past, present and future infringement; and the right to collect and retain all damages collected or awarded thereunder;

We warrantee that the undersigned have the full right to convey the entire interest herein assigned;

We authorize and request the Commissioner of Patents and Trademarks, and any Official of any country whose duty it is to issue patents on applications as aforesaid, to issue said Letters Patent to said Assignee; and

We agree to sign all lawful papers, make all rightful oaths, do all lawful acts requisite for such patents, and do everything possible to aid said Assignee to apply for, obtain and enforce patent protection for said inventions.

Signed: 

Yotam Stern
Director

Amitec - Advanced Multilayer Interconnect Technologies Ltd.

AMITEC-ADVANCED MULTILAYER
INTERCONNECT TECHNOLOGIES LTD

Dated: August 3, 2011

PATENT

REEL: 026698 FRAME: 0580

**RECORDATION FORM COVER SHEET
PATENTS ONLY**Attorney Docket No.: **AMIT 1047/901**

To the Honorable Commissioner of patents and Trademarks: Please record the attached documents or the new address(es) below.

1. Name of conveying party(ies):

**Amitec-Advanced Multilayer
Interconnect Technologies Ltd.**

Additional name(s) of conveying party(ies) attached?

☐ Yes ☒ No

3. Nature of conveyance:

☒ Assignment☐ Merger☐ Security☐ Change of Name☐ Other _____

2. Name and address of receiving party(ies)

**Name: Zhuhai Advanced Chip Carriers &
Electronic Substrate Solutions Technologies
Co. Ltd.,**

Internal Address: _____

Street Address: _____

**FounderPCB Industry Park, Fushan Industry
Zone, Qianwu, Doumen**City: **Zhuhai** State: _____Country: **P.R. China** ZIP: **519173**

Additional name(s) & address(es) attached?

☐ Yes ☒ No3. Execution Date: **August 3, 2011**4. Application number(s) or patent number(s): **7,635,641; 7,669,320; 7,682,972**☐ This document is being filed together with a new application.

A. Patent Application No.(s)

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No5. Name and address of party to whom
correspondence concerning document should be
mailed:Name: **JMB, Factor & Co.**

Internal Address: _____

Street Address: **One Hamarpe Street****Har Hotzvim**City: **Jerusalem**State: **Israel** ZIP: **91450**Tel: **+972-2-571-4777**Fax: **+972-2-571-4455**E-mail: **patents@israel-patents.co.il**6. Total number of applications and
patents involved: **3**7. Total fee (37 CFR 1.21(h) & 3.41) \$ **120**☐ Check no. _____ is attached
☒ Authorized to be charged by credit card

8. Payment Information:

a. Credit card Last 4 Numbers: **7010**Expiration Date: **2.14.14**

b. Deposit account number:

Authorized User Name:

9. Signature.

Yotam STERN, Director

Name of Person Signing

/Yotam STERN/

Signature

August 4, 2011

Date

Total number of pages including cover sheet, attachments, and document: